











LM4041-N, LM4041-N-Q1

SNOS641G - OCTOBER 1999-REVISED JANUARY 2016

LM4041-N-xx Precision Micropower Shunt Voltage Reference

Features

- **Qualified for Automotive Applications**
- SEC-Q100 Qualified With the Following Results:
 - Device Temperature Grade 1: –40°C to +125°C Ambient Temperature Range
 - Device Temperature Grade 3: –40°C to +85°C Ambient Temperature Range (For SOT-23 Only)
- Available in Standard, AEC Q-100 Grade 1 (Extended Temperature Range), and Grade 3 (Industrial Temperature Range) Qualified Versions (SOT-23 Only)
- Small Packages: SOT-23, TO-92, and SC70
- No Output Capacitor Required
- **Tolerates Capacitive Loads**
- Reverse Breakdown Voltage Options of 1.225 V and Adjustable
- Output Voltage Tolerance (A grade, 25°C) = ±0.1%(Maximum)
- Low Output Noise (10 Hz to 10kHz) = $20 \mu V_{rms}$
- Wide Operating Current Range of 60 µA to 12 mA
- Industrial Temperature Range (LM4041A/B-N, LM4041-N-Q1A/Q1B) of -40°C to +85°C
- Extended Temperature Range (LM4041C/D/E-N, LM4041-N-Q1C/Q1D/Q1E) of -40°C to +125°C
- Low Temperature Coefficient of 100 ppm/°C (Maximum)

2 Applications

- Portable, Battery-Powered Equipment
- **Data Acquisition Systems**
- Instrumentation
- **Process Control**
- **Energy Management**
- Automotive
- **Precision Audio Components**

3 Description

Ideal for space-critical applications, the LM4041-N precision voltage reference is available in the sub-SC70 and SOT-23 surface-mount packages. The advanced design of the LM4041-N eliminates the need for an external stabilizing capacitor while ensuring stability with any capacitive load, thus making the LM4041-N easy to use. Further reducing design effort is the availability of a fixed (1.225 V) and adjustable reverse breakdown voltage. The minimum operating current is 60 µA for the LM4041-N 1.2 and the LM4041-N ADJ. Both versions have a maximum operating current of 12 mA.

The LM4041-N uses fuse and Zener-zap reverse breakdown or reference voltage trim during wafer sort to ensure that the prime parts have an accuracy of better than ±0.1% (A grade) at 25°C. Bandgap reference temperature drift curvature correction and low dynamic impedance ensure stable reverse breakdown voltage accuracy over a wide range of operating temperatures and currents.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
	SC70 (5)	1.25 mm × 2.00 mm
LM4041-N	SOT-23 (3)	1.30 mm × 2.92 mm
	TO-92 (3)	4.30 mm × 4.30 mm
LM4041-N-Q1	SOT-23 (3)	1.30 mm × 2.92 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

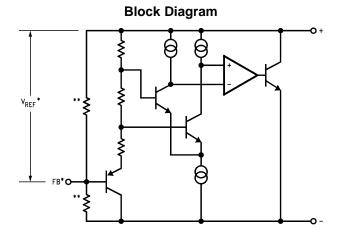




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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision F (July 2013) to Revision G

Page

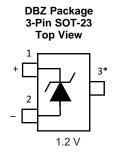
 Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section

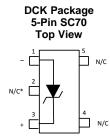
Changes from Revision D (April 2013) to Revision E

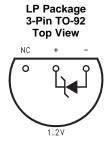
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5 Pin Configuration and Functions





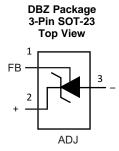


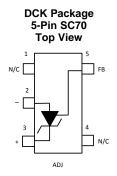
Pin Functions

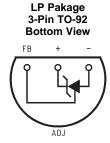
	PIN				DESCRIPTION						
NAME	SOT-23	SC70	TO-92	1/0	DESCRIPTION						
Anode	2	1	1	0	Anode pin, normally grounded						
Cathode	1	3	2	I/O	Shunt current and output voltage						
FB	_	_	_	1	Feedback pin for adjustable output voltage						
NC**	3	2	_	_	**Must float or connect to anode						
NC	_	4, 5	3	_	No connect						

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Pin Functions: ADJ Pinouts

	PIN	l		1/0	DESCRIPTION		
NAME	SOT-23	SC70	TO-92	I/O	DESCRIPTION		
Anode	3	2	1	0	Anode pin, normally grounded		
Cathode	2	3	2	I/O	Shunt current and output voltage		
FB	1	5	3	I	Feedback pin for adjustable output voltage		
NC**	_	_	_	_	**Must float or connect to anode		
NC	_	1, 4	_	_	No connect		

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)(2)

			MIN	MAX	UNIT
Reverse current				20	mA
Forward current				10	mA
Maximum output voltage ((LM4041-N ADJ, LM4041-N	I-Q1 ADJ)		15	V
		DBZ package		306	mW
Power dissipation (T _A = 25	5°C) ⁽³⁾	LP package		550	mW
		DCK package		241	mW
	DD7	Vapor phase (60 seconds)		215	°C
Lead temperature	DBZ packages	Infrared (15 seconds)		220	°C
	LP package	Soldering (10 seconds)		260	°C
Storage temperature, T _{stg}			-65	150	°C

- (1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/ Distributors for availability and specifications.
- The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{Jmax} (maximum junction temperature), θ_{JA} (junction to ambient thermal resistance), and T_A (ambient temperature). The maximum allowable power dissipation at any temperature is PD_{max} = (T_{Jmax} T_A)/R_{θ,JA} or the number given in the *Absolute Maximum Ratings*, whichever is lower. For the LM4041-N, T_{Jmax} = 125°C, and the typical thermal resistance (R_{θ,JA}), when board mounted, is 326°C/W for the SOT-23 package, 415°C/W for the SC70 package and 180°C/W with 0.4-in lead length and 170°C/W with 0.125-in lead length for the TO-92 package.

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6.2 ESD Ratings

			VALUE	UNIT
		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)(2)	±2000	
V _(ESD)	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽³⁾	±200	V
	diconargo	Machine model (MM)	±200	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) The human-body model is a 100-pF capacitor discharged through a 1.5-kΩ resistor into each pin. The machine model is a 200-pF capacitor discharged directly into each pin. All pins are rated at 2 kV for human-body model, but the feedback pin which is rated at 1 kV.
- (3) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 250-V CDM is possible with the necessary precautions.

6.3 Recommended Operating Conditions

See (1)

		MIN	NOM	MAX	UNIT
Temperature		T _{min}	T_A	T_{max}	°C
Industrial temperature		-40	T_A	85	°C
Extended temperature		-40	T _A	125	°C
Davissa sumant	LM4041-N 1.2, LM4041-N-Q1 1.2	60		1200	μΑ
Reverse current	LM4041-N ADJ, LM4041-N-Q1 ADJ	60		1200	μΑ
Output voltage	LM4041-N ADJ, LM4041-N-Q1 ADJ	1.24		10	V

⁽¹⁾ Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Recommended Operating Conditions indicate conditions for which the device is functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics. The ensured specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

6.4 Thermal Information

	(1)	LM4	041-N	LM4041-N, LM4041-N-Q1	
	THERMAL METRIC ⁽¹⁾	SC70	TO-92	SOT-23	UNIT
		5 PINS	3 PINS	3 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	265.3	161.5	291.9	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	93.1	84.5	114.3	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	46.7	_	62.3	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	2.2	28.4	7.4	°C/W
ΨЈВ	Junction-to-board characterization parameter	45.9	140.6	61	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	_	_	_	°C/W

 For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report, SPRA953.

Product Folder Links: LM4041-N LM4041-N-Q1



6.5 LM4041-N-xx 1.2 Electrical Characteristics (Industrial Temperature Range)

All limits $T_A = T_J = 25^{\circ}\text{C}$ for the LM4041xAIM3, LM4041xBIM3, LM4041AIZ, LM4041BIZ and LM4041BIM7 devices, unless otherwise specified. The grades A and B designate initial reverse breakdown voltage tolerances of $\pm 0.1\%$ and $\pm 0.2\%$, respectively.

	PARAMETER	TEST	CONDITIONS	MIN ⁽¹⁾ TY	P ⁽²⁾	MAX ⁽¹⁾	UNIT
	Reverse breakdown voltage	I _R = 100 μA		1.	225		٧
		1 400 4	LM4041AIM3, LM4041QAIM3 LM4041AIM3, LM4041AIZ			±1.2	
V_{R}	Reverse breakdown	I _R = 100 μA	LM4041BIM3, LM4041QBIM3 LM4041BIZ, LM4041BIM7			±2.4	\ <i>(</i>
	voltage tolerance (3)		LM4041AIM3, LM4041QAIM3 LM4041AIM3, LM4041AIZ			±9.2	mV
		$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041BIM3, LM4041QBIM3 LM4041BIZ, LM4041BIM7			±10.4	
_	Minimum operating	$T_A = T_J = 25$ °C			45	60	
I _{RMIN}	current	$T_A = T_J = T_{MIN}$ to T_{MAX}				65	μA
	Average reverse	I _R = 10 mA		±20			
$\Delta V_R/\Delta T$	breakdown voltage temperature Coefficient (3)	I _R = 1 mA	$T_A = T_J = 25$ °C		±15		ppm/°C
ΔVR/ΔI		IR = I IIIA	$T_A = T_J = T_{MIN}$ to T_{MAX}			±100	:100
	Coemcient	I _R = 100 μA		±15			
	Reverse breakdown	$I_{RMIN} \le I_R \le 1 \text{ mA}$	$T_A = T_J = 25$ °C		0.7	1.5	
$\Delta V_R/\Delta I_R$	voltage change with	IRMIN = IR = 1 IIIA	$T_A = T_J = T_{MIN}$ to T_{MAX}			2	mV
ΔVR/ΔIR	operating current change ⁽⁴⁾	1 mA ≤ I _R ≤ 12 mA	$T_A = T_J = 25$ °C		4	6	IIIV
	current change	1 111/2 1 _R = 12 111/	$T_A = T_J = T_{MIN}$ to T_{MAX}			8	
Z_R	Reverse dynamic impedance	$I_R = 1 \text{ mA}, f = 120 \text{ Hz}, I_{AC} = 0.1 I_R$			0.5	1.5	Ω
e _N	Wideband noise	I _R = 100 μA 10 Hz ≤ f ≤ 10 kHz			20		μV_{rms}
ΔV_R	Reverse breakdown voltage long-term stability	t = 1000 hrs T = 25°C ±0.1°C I _R = 100 μA			120		ppm
V _{HYST}	Thermal hysteresis (5)	$\Delta T = -40$ °C to +125°C		0.0	08%		

⁽¹⁾ Limits are 100% production tested at 25°C. Limits over temperature are ensured through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate AOQL.

(2) Typicals are at $T_J = 25^{\circ}$ C and represent most likely parametric norm.

A-grade: $\pm 0.75\% = \pm 0.1\% \pm 100 \text{ ppm/°C} \times 65^{\circ}\text{C}$

B-grade: $\pm 0.85\% = \pm 0.2\% \pm 100 \text{ ppm/°C} \times 65^{\circ}\text{C}$

C-grade: $\pm 1.15\% = \pm 0.5\% \pm 100 \text{ ppm/°C} \times 65^{\circ}\text{C}$

D-grade: $\pm 1.98\% = \pm 1.0\% \pm 150 \text{ ppm/°C} \times 65^{\circ}\text{C}$

E-grade: $\pm 2.98\% = \pm 2.0\% \pm 150 \text{ ppm/°C} \times 65^{\circ}\text{C}$

The total over-temperature tolerance for the different grades in the extended temperature range where max $\Delta T = 100$ °C is shown below:

B-grade: $\pm 1.2\% = \pm 0.2\% \pm 100 \text{ ppm/°C} \times 100 \text{°C}$

C-grade: $\pm 1.5\% = \pm 0.5\% \pm 100 \text{ ppm/°C} \times 100°C$

D-grade: $\pm 2.5\% = \pm 1.0\% \pm 150 \text{ ppm/°C} \times 100^{\circ}\text{C}$

E-grade: $\pm 4.5\% = \pm 2.0\% \pm 150 \text{ ppm/°C} \times 100°C$

Therefore, as an example, the \dot{A} -grade LM4041-N 1.2 has an over-temperature Reverse Breakdown Voltage tolerance of ± 1.2 V \times 0.75% = ± 9.2 mV.

- (4) Load regulation is measured on pulse basis from no load to the specified load current. Output changes due to die temperature change must be taken into account separately.
- (5) Thermal hysteresis is defined as the difference in voltage measured at +25°C after cycling to temperature -40°C and the +25°C measurement after cycling to temperature +125°C.

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The overtemperature limit for Reverse Breakdown Voltage Tolerance is defined as the room temperature Reverse Breakdown Voltage Tolerance ±[(ΔV_R ΔT)(max ΔT)(V_R)]. Where, ΔV_R/ΔT is the V_R temperature coefficient, maxΔT is the maximum difference in temperature from the reference point of 25 °C to T MAX or TMIN, and V_R is the reverse breakdown voltage. The total over-temperature tolerance for the different grades in the industrial temperature range where maxΔT = 65°C is shown below:



6.6 LM4041-N-xx 1.2 Electrical Characteristics (Industrial Temperature Range)

All limits $T_A = T_J = 25^{\circ}$ C. unless otherwise specified. The grades C, D, and E designate initial reverse breakdown voltage tolerances of $\pm 0.5\%$, $\pm 1.0\%$, and $\pm 2.0\%$, respectively.

P	ARAMETER		TEST CONDITIO	NS	MIN ⁽¹⁾	TYP ⁽²⁾	MAX ⁽¹⁾	UNIT
	Reverse Breakdown Voltage	Ι _R = 100 μΑ				1.225		٧
				LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7			±6	
		breakdown voltage I _R = 100 μA	$T_A = T_J = 25$ °C	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7			±12	
V_{R}	Reverse breakdown			LM4041EIM3, LM4041QEIM3, LM4041EIZ, LM4041EIM7			±25	
	voltage tolerance ⁽³⁾			LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7			±14	mV
			$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7			±24	
				LM4041EIM3, LM4041QEIM3, LM4041EIZ, LM4041EIM7	=	±36		
		LM4041CIM3, LM4041QCIM3, LM4041CIM7 T _A = T _J = 25°C LM4041DIM3, LM4041DIM3, LM4041DIM7, LM4041DIM3, LM4041DIM3, LM4041DIM3, LM4041EIM3, LM4041EIM3, LM4041EIM3, LM4041EIM7				45	60	
	Minimum			LM4041DIZ, LM4041DIM7 LM4041EIM3, LM4041QEIM3,			65	
I _{RMIN}	operating current			LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7			65	μA
		$T_A = T_J = T_{MIN}$ to T_{MA}	· ·	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7 LM4041EIM3, LM4041QEIM3, LM4041EIZ, LM4041EIM7			70	
		I _R = 10 mA				±20		
			$T_A = T_J = 25$ °C			±15		
	V _R Temperature	$I_R = I_R MA$		LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7			±100	/00
$\Delta V_R / \Delta T$	coefficient ⁽³⁾				LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7 LM4041EIM3, LM4041QEIM3, LM4041EIZ, LM4041EIM7			±150
		I _R = 100 μA				±15		

A-grade: $\pm 0.75\% = \pm 0.1\% \pm 100 \text{ ppm/°C} \times 65^{\circ}\text{C}$ B-grade: $\pm 0.85\% = \pm 0.2\% \pm 100 \text{ ppm/°C} \times 65^{\circ}\text{C}$ C-grade: $\pm 1.15\% = \pm 0.5\% \pm 100 \text{ ppm/°C} \times 65^{\circ}\text{C}$ D-grade: $\pm 1.98\% = \pm 1.0\% \pm 150 \text{ ppm/°C} \times 65^{\circ}\text{C}$

E-grade: $\pm 2.98\% = \pm 2.0\% \pm 150 \text{ ppm/°C} \times 65^{\circ}\text{C}$

The total over-temperature tolerance for the different grades in the extended temperature range where max $\Delta T = 100$ °C is shown below.

B-grade: $\pm 1.2\% = \pm 0.2\% \pm 100 \text{ ppm/}^{\circ}\text{C} \times 100^{\circ}\text{C}$ C-grade: $\pm 1.5\% = \pm 0.5\% \pm 100 \text{ ppm/}^{\circ}\text{C} \times 100^{\circ}\text{C}$ D-grade: $\pm 2.5\% = \pm 1.0\% \pm 150 \text{ ppm/}^{\circ}\text{C} \times 100^{\circ}\text{C}$ E-grade: $\pm 4.5\% = \pm 2.0\% \pm 150 \text{ ppm/}^{\circ}\text{C} \times 100^{\circ}\text{C}$

Therefore, as an example, the A-grade LM4041-N 1.2 has an over-temperature reverse breakdown voltage tolerance of ±1.2 V × 0.75%

 $= \pm 9.2 \text{ mV}.$

⁽¹⁾ Limits are 100% production tested at 25°C. Limits over temperature are ensured through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate AOQL.

⁽²⁾ Typicals are at $T_J = 25^{\circ}C$ and represent most likely parametric norm.

⁽³⁾ The overtemperature limit for reverse breakdown voltage tolerance is defined as the room temperature reverse breakdown voltage tolerance ±[(ΔV_R ^γΔT)(max ΔT)(V_R)]. Where, ΔV_R/ΔT is the V_R temperature coefficient, maxΔT is the maximum difference in temperature from the reference point of 25 °C to T _{MAX} or T_{MIN}, and V_R is the reverse breakdown voltage. The total over-temperature tolerance for the different grades in the industrial temperature range where maxΔT = 65°C is shown below:



LM4041-N-xx 1.2 Electrical Characteristics (Industrial Temperature Range) (continued)

All limits $T_A = T_J = 25$ °C. unless otherwise specified. The grades C, D, and E designate initial reverse breakdown voltage tolerances of $\pm 0.5\%$, $\pm 1.0\%$, and $\pm 2.0\%$, respectively.

P	ARAMETER		TEST CONDITIO	ons	MIN ⁽¹⁾	TYP ⁽²⁾	MAX ⁽¹⁾	UNIT
				LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7		0.7	1.5	
		$T_{A} = T_{J} = 25^{\circ}C$ $I_{RMIN} \leq I_{R} \leq 1 \text{ mA}$	$T_A = T_J = 25^{\circ}C$	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7 (LM4041EIM3, LM4041QEIM3, LM4041EIZ, LM4041EIM7			2	mV
			LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7			2	mv	
Reverse breakdown	$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7 LM4041EIM3, LM4041QEIM3, LM4041EIZ, LM4041EIM7)			2.5			
$\Delta V_R / \Delta I_R$	voltage change with operating current change ⁽⁴⁾			LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7		2.5	6	
		1 mA ≤ I _R ≤ 12 mA	$T_A = T_J = 25$ °C	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7 LM4041EIM3, LM4041QEIM3, LM4041EIZ, LM4041EIM7			8	- mV
			$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7			8	
				LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7 LM4041EIM3, LM4041QEIM3, LM4041EIZ, LM4041EIM7			10	
				LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7		0.5	1.5	
Z _R	Reverse dynamic impedance	$I_R = 1 \text{ mA}, f = 120 \text{ Hz}$ $I_{AC} = 0.1 I_R$		LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7 LM4041EIM3, LM4041QEIM3, LM4041EIZ, LM4041EIM7			2	Ω
e _N	Wideband noise	I _R = 100 μA 10 Hz ≤ f ≤ 10 kHz		·		20		μV_{rms}
ΔV_{R}	Reverse breakdown voltage long-term stability	t = 1000 hrs T = 25°C ±0.1°C I _R = 100 μA				120		ppm
V _{HYST}	Thermal hysteresis ⁽⁵⁾	$\Delta T = -40$ °C to +125°C				0.08%		

⁽⁴⁾ Load regulation is measured on pulse basis from no load to the specified load current. Ouput changes due to die temperature change must be taken into account separately.

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⁽⁵⁾ Thermal hysteresis is defined as the difference in voltage measured at +25°C after cycling to temperature -40°C and the +25°C measurement after cycling to temperature +125°C.



6.7 LM4041-N-xx 1.2 Electrical Characteristics (Extended Temperature Range)

All limits T_A = T_J = 25°C, unless otherwise specified. The grades C, D, and E designate initial reverse breakdown voltage tolerance of ±0.5%, ±1.0%, and ±2.0% respectively.

PAF	RAMETER		TEST CONDITIONS		MIN ⁽¹⁾	TYP ⁽²⁾	MAX ⁽¹⁾	UNIT
	Reverse breakdown voltage	Ι _R = 100 μΑ				1.225		V
				LM4041CEM3, LM4041QCEM3			±6	
			$T_A = T_J = 25^{\circ}C$	LM4041DEM3, LM4041QDEM3			±12	
V_R	breakdown	1 100		LM4041EEM3, LM4041QEEM3			±25	\
	voltage error ⁽³⁾	I _R = 100 μA		LM4041CEM3, LM4041QCEM3			±18.4	mV
			$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041DEM3, LM4041QDEM3		±3	±31	
				LM4041EEM3, LM4041QEEM3			±43	
				LM4041CEM3, LM4041QCEM3		45	60	60
	Minimum	$T_A = T_J = 25^{\circ}C$		LM4041DEM3, LM4041QDEM3 LM4041EEM3, LM4041QEEM3			65	
I _{RMIN}	operating current			LM4041CEM3, LM4041QCEM3			68	μΑ
		LM4041EEM3, LM4041QEEM3		LM4041DEM3, LM4041QDEM3 LM4041EEM3, LM4041QEEM3			73	
		LM4041EEM3, LM4041QEEM3				±20		
			$T_A = T_J = 25^{\circ}C$			±15		
VR $\Delta V_R/\Delta T$ temperat coefficier				LM4041CEM3, LM4041QCEM3			±100	<i>-</i>
	temperature coefficient ⁽³⁾	perature fficient (3) $I_R = 1 \text{ mA}$ $T_A = T_J = T_{MIN} \text{ to } T_{MIN} = T_{MIN} \text{ fo } T_{MIN} = T_{MIN} = T_{MIN} \text{ fo } T_{MIN} = T_{MIN} = T_{MIN} \text{ fo } T_{MIN}$	$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041DEM3, LM4041QDEM3 LM4041EEM3, LM4041QEEM3			±150	ppm/°C
		LM4041EEM3, LM4041QEEM3				±15		

A-grade: $\pm 0.75\% = \pm 0.1\% \pm 100 \text{ ppm/°C} \times 65^{\circ}\text{C}$ B-grade: $\pm 0.85\% = \pm 0.2\% \pm 100 \text{ ppm/°C} \times 65^{\circ}\text{C}$ C-grade: $\pm 1.15\% = \pm 0.5\% \pm 100 \text{ ppm/°C} \times 65°C$

D-grade: $\pm 1.98\% = \pm 1.0\% \pm 150 \text{ ppm/°C} \times 65^{\circ}\text{C}$ E-grade: $\pm 2.98\% = \pm 2.0\% \pm 150 \text{ ppm/°C} \times 65^{\circ}\text{C}$

The total over-temperature tolerance for the different grades in the extended temperature range where max $\Delta T = 100$ °C is shown

B-grade: $\pm 1.2\% = \pm 0.2\% \pm 100 \text{ ppm/°C} \times 100 \text{°C}$ C-grade: $\pm 1.5\% = \pm 0.5\% \pm 100 \text{ ppm/°C} \times 100 \text{°C}$ D-grade: $\pm 2.5\% = \pm 1.0\% \pm 150 \text{ ppm/°C} \times 100°C$ E-grade: $\pm 4.5\% = \pm 2.0\% \pm 150 \text{ ppm/°C} \times 100°C$

Therefore, as an example, the A-grade LM4041-N 1.2 has an over-temperature reverse breakdown voltage tolerance of ±1.2 V × 0.75%

= +9.2 mV

⁽¹⁾ Limits are 100% production tested at 25°C. Limits over temperature are ensured through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate AOQL.

⁽²⁾ Typicals are at $T_J = 25^{\circ}C$ and represent most likely parametric norm.

⁽³⁾ The overtemperature limit for reverse breakdown voltage tolerance is defined as the room temperature reverse breakdown voltage tolerance $\pm [(\dot{\Delta} V_R \dot{r} \Delta T)(max \Delta T)(V_R)]$. Where, $\Delta V_R \dot{\Delta} T$ is the V_R temperature coefficient, max ΔT is the maximum difference in temperature from the reference point of 25 °C to T MAX or TMIN, and VR is the reverse breakdown voltage. The total over-temperature tolerance for the different grades in the industrial temperature range where max $\Delta T = 65^{\circ}$ C is shown below:



LM4041-N-xx 1.2 Electrical Characteristics (Extended Temperature Range) (continued)

All limits $T_A = T_J = 25$ °C, unless otherwise specified. The grades C, D, and E designate initial reverse breakdown voltage tolerance of ±0.5%, ±1.0%, and ±2.0% respectively.

PAF	RAMETER		TEST CONDITIONS		MIN ⁽¹⁾	TYP ⁽²⁾	MAX ⁽¹⁾	UNIT
				LM4041CEM3, LM4041QCEM3		0.7	1.5	
			$T_A = T_J = 25$ °C	LM4041DEM3, LM4041QDEM3 LM4041EEM3, LM4041QEEM3			2	mV
		$I_{RMIN} \le I_R \le 1.0 \text{ mA}$		LM4041CEM3, LM4041QCEM3			2	IIIV
A./. /A.I	Reverse breakdown		LM4041EEM3, LM4041QEEM3	LM4041DEM3, LM4041QDEM3 M4041EEM3, LM4041QEEM3			2.5	
$\Delta V_R / \Delta I_R$	change with current (4)			LM4041CEM3, LM4041QCEM3		2.5	6	
		1 mA ≤ I _R ≤ 12 mA	LM4041EEM3, LM4041QEEM3	LM4041DEM3, LM4041QDEM3 LM4041EEM3, LM4041QEEM3			8	
				LM4041CEM3, LM4041QCEM3			8	mV
			LM4041EEM3, LM4041QEEM3	LM4041DEM3, LM4041QDEM3 LM4041EEM3, LM4041QEEM3			10	
			$T_A = T_J = 25^{\circ}C$			0.5		
	Reverse	I _R = 1 mA, f = 120 Hz,		LM4041CEM3, LM4041QCEM3			1.5	
Z _R	dynamic impedance	I _{AC} = 0.1 I _R	$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041DEM3, LM4041QDEM3 LM4041EEM3, LM4041QEEM3			2	Ω
e _N	Noise voltage	I _R = 100 μA 10 Hz ≤ f ≤ 10 kHz				20		μV_{rms}
ΔV_R	Long-term stability (non-cumulative)					120		ppm
V _{HYST}	Thermal hysteresis (5)	$\Delta T = -40$ °C to +125°C				0.08%		

⁽⁴⁾ Load regulation is measured on pulse basis from no load to the specified load current. Ouput changes due to die temperature change must be taken into account separately.

Thermal hysteresis is defined as the difference in voltage measured at +25°C after cycling to temperature –40°C and the +25°C

measurement after cycling to temperature +125°C.



6.8 LM4041-N-xx ADJ (Adjustable) Electrical Characteristics (Industrial Temperature Range)

All limits $T_J = 25$ °C, unless otherwise specified (SOT-23, see⁽¹⁾),

 $I_{RMIN} \le I_R \le 12$ mA, $V_{REF} \le V_{OUT} \le 10$ V. The grades C and D designate initial Reference Voltage Tolerances of $\pm 0.5\%$ and $\pm 1\%$, respectively for $V_{OUT} = 5$ V.

PARA	METER		TEST CONDITION	S	MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
	Reference voltage	I _R = 100 μA, V _{OUT} = 5 V				1.233		V
			T 059C	LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7			±6.2	
V_{REF}	Reference	1 400 1	T _J = 25°C	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7			±12	\/
	voltage tolerance ⁽⁴⁾	$I_R = 100 \mu A, V_{OUT} = 5 V$	T T T 4- T	LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7			±14	mV
			$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7			±24	
		T 25%		LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7		45	60	
	Minimum	T _J = 25°C		LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7			65	
I _{RMIN}	operating current	T _ T _ T _ to T		LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7			65	μA
		$T_A = T_J = T_{MIN}$ to T_{MAX}		LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7			70	
			T 250C	LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7		0.7	1.5	
		$I_{RMIN} \le I_R \le 1 \text{ mA}$	T _J = 25°C	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7			2	mV
	Reference voltage change with	SOT-23: V _{OUT} ≥ 1.6 V ⁽¹⁾	T - T - T to T	LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7			2	mv
$\Delta V_{REF}/\Delta I_{R}$			$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7			2.5	
ΔV _{REF} /ΔI _R	operating current change (5)		T _ 25°C	LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7		2	4	
	change	1 mA ≤ I _R ≤ 12 mA	T _J = 25°C	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7			6	mV
		SOT-23: V _{OUT} ≥ 1.6 V ⁽¹⁾	T - T - T to T	LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7			6	IIIV
			$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7			8	
	Reference		T _J = 25°C	LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7		-1.55	-2	
۸۱/ /۸۱/	voltage change with	1 m Λ	11 = 23 0	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7			-2.5	mV/V
^{Δν} REF ^{/Δν} Ο Οι νο	output voltage	I _R = 1 mA	T - T - T to T	LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7			-2.5	IIIV/V
	change		$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7			-3	
		T = 25°C		LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7		60	100	
I _{FB}	Feedback current	T _J = 25°C LM4041DIM3, LM4041QDIM3, LM4041DIM7					150	nA
		$T_A = T_J = T_{MIN}$ to T_{MAX}					120	

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⁽¹⁾ When V_{OUT} ≤ 1.6 V, the LM4041-N ADJ in the SOT-23 package must operate at reduced I_R. This is caused by the series resistance of the die attach between the die (–) output and the package (–) output pin. See the Output Saturation (SOT-23 only) curve in the Typical Characteristics section.

⁽²⁾ Limits are 100% production tested at 25°C. Limits over temperature are ensured through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate AOQL.

⁽³⁾ Typicals are at $T_J = 25$ °C and represent most likely parametric norm.

⁽⁴⁾ Reference voltage and temperature coefficient will change with output voltage. See Typical Characteristics curves.

⁽⁵⁾ Load regulation is measured on pulse basis from no load to the specified load current. Ouput changes due to die temperature change must be taken into account separately.



LM4041-N-xx ADJ (Adjustable) Electrical Characteristics (Industrial Temperature Range) (continued)

All limits $T_J = 25$ °C, unless otherwise specified (SOT-23, see⁽¹⁾),

 $I_{RMIN} \le I_R \le 12$ mA, $V_{REF} \le V_{OUT} \le 10$ V. The grades C and D designate initial Reference Voltage Tolerances of $\pm 0.5\%$ and $\pm 1\%$, respectively for $V_{OUT} = 5$ V.

PARA	METER		TEST COND	ITIONS		MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
			I _R = 10 mA				20		
				$T_J = 25^{\circ}C$			15		
$\Delta V_{REF}/\Delta T$	Average reference voltage	V _{OUT} = 5 V	I _R = 1 mA	$T_A = T_J =$	LM4041CIM3, LM4041QCIM3, LM4041CIZ, LM4041CIM7			±100	ppm/°C
	temperature coefficient (4)			T _{MIN} to T _{MAX}	LM4041DIM3, LM4041QDIM3, LM4041DIZ, LM4041DIM7			±150	
			I _R = 100 μA			15			
	Dynamic	I_R = 1 mA, f = 120 Hz, I_{AC}	= 0.1 I _R				0.3		
Z _{OUT}	output impedance	V _{OUT} = V _{REF} V _{OUT} = 10 V					2		Ω
e _N	Wideband noise	$V_{OUT} = V_{REF} I_R = 100 \mu A 1$	0 Hz ≤ f ≤ 10 kHz				20		μV_{rms}
ΔV_{REF}	Reference voltage long-term stability	t = 1000 hrs, I _R = 100 μA, T = 25°C ±0.1°C					120		ppm
V _{HYST}	Thermal hysteresis ⁽⁶⁾	$\Delta T = -40^{\circ}C \text{ to } +125^{\circ}C$					0.08%		

⁽⁶⁾ Thermal hysteresis is defined as the difference in voltage measured at +25°C after cycling to temperature -40°C and the +25°C measurement after cycling to temperature +125°C.

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6.9 LM4041-N-xx ADJ (Adjustable) Electrical Characteristics (Extended Temperature Range)

All limits $T_J = 25^{\circ}$ C, unless otherwise specified (SOT-23, see⁽¹⁾), $I_{RMIN} \le I_R \le 12$ mA, $V_{REF} \le V_{OUT} \le 10$ V. The grades C and D designate initial Reference Voltage Tolerances of ±0.5% and ±1%, respectively for $V_{OUT} = 5$ V.

PA	RAMETER		TEST C	ONDITIONS		MIN ⁽²⁾	TYP(3)	MAX ⁽²⁾	UNIT
	Reference voltage	$I_R = 100 \mu A, V_{OUT} = 5$	5 V				1.233		٧
			T 0500	LM4041CEM3, LM404	1QCEM3			±6.2	
V_{REF}	Reference voltage	I _R = 100 μA, V _{OUT} =	T _J = 25°C	LM4041DEM3, LM404	1QDEM3			±12	,
	tolerance ⁽⁴⁾	5 V	T T T 1- T	LM4041CEM3, LM404	1QCEM3			±18	mV
			$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041DEM3, LM404	1QDEM3			±30	
		T 0500	1	LM4041CEM3, LM404	1QCEM3		45	60	
	Minimum	T _J = 25°C		LM4041DEM3, LM404	1QDEM3			65	
I _{RMIN}	operating current	T T T 1- T		LM4041CEM3, LM404	1QCEM3			68	μΑ
		$T_A = T_J = T_{MIN}$ to T_{MA}	X	LM4041DEM3, LM404	1QDEM3			73	
			T ₁ = 25°C	LM4041CEM3, LM404	1QCEM3		0.7	1.5	
ı		$I_{RMIN} \le I_R \le 1 \text{ mA}$	I _J = 25°C	LM4041DEM3, LM404	1QDEM3			2	
		SOT-23: V _{OUT} ≥ 1.6 V ⁽¹⁾	T T T 1- T	LM4041CEM3, LM404	1QCEM3			2	mV
A)/ /AI	Reference voltage change with		$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041DEM3, LM404	1QDEM3			2.5	
$\Delta V_{REF}/\Delta I_{R}$	operating current change ⁽⁵⁾		T 0500	LM4041CEM3, LM404	1QCEM3		2	8	
	current change	1 mA ≤ I _R ≤ 12 mA	T _J = 25°C	LM4041DEM3, LM404	1QDEM3			10	
		SOT-23: V _{OUT} ≥ 1.6 V ⁽¹⁾	T T T 40 T	LM4041CEM3, LM4041QCEM3				6	mV
			IA = IJ = I _{MIN} to I _{MAX}	LM4041DEM3, LM404	1QDEM3			8	
	Defense		T ₁ = 25°C	LM4041CEM3, LM404	1QCEM3		-1.55	-2	
A\/ /A\/	Reference voltage change with	I _R = 1 mA	1 _J = 25 C	LM4041DEM3, LM404	1QDEM3			-2.5	mV/V
Δv _{REF} /Δv _O	output voltage	I _R = 1 IIIA	$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041CEM3, LM404	1QCEM3			-3	IIIV/V
	change		TA = TJ = TMIN tO TMAX	LM4041DEM3, LM404	1QDEM3			-4	
		T _{.1} = 25°C		LM4041CEM3, LM404		60	100		
1	Feedback current	1 _J = 25 C		LM4041DEM3, LM404	1QDEM3			150	nA
I _{FB}	i eeuback cuiteiti	$T_A = T_{.I} = T_{MIN}$ to T_{MA}		LM4041CEM3, LM404	1QCEM3			120	IIA
		IA - IJ - IMIN tO IMA	X	LM4041DEM3, LM404	1QDEM3			200	<u></u>
			I _R = 10 mA				20		
	Average			T _J = 25°C			15		
$\Delta V_{REF}/\Delta T$	reference voltage	V _{OUT} = 5 V,	I _R = 1 mA	$T_A = T_J = T_{MIN}$ to T_{MAX}	LM4041CEM3, LM4041QCEM3			±100	ppm/°C
	temperature coefficient ⁽⁴⁾			TA - TJ - TMIN to TMAX	LM4041DEM3, LM4041QDEM3			±150	
			I _R = 100 μA				15		i
		I _R = 1 mA, f = 120 Hz	7 ,						
7	Dynamic output	$I_{AC} = 0.1 I_{R}$				0.3		Ω	
Z _{OUT}	impedance		$V_{OUT} = V_{REF}$						12
			V _{OUT} = 10 V				2		
0	Wideband noise	$I_R = 100 \ \mu A$,	$V_{OUT} = V_{REF}$				20		/
e _N	vvideballu lioise	10 Hz ≤ f ≤ 10 kHz					20		μV_{rms}
ΔV_{REF}	Reference voltage long-term stability	t = 1000 hrs, I _R = 100 T = 25°C ±0.1°C) μA,				120		ppm
V _{HYST}	Thermal hysteresis (6)	ΔT = -40°C to +125°	С			0.08%			

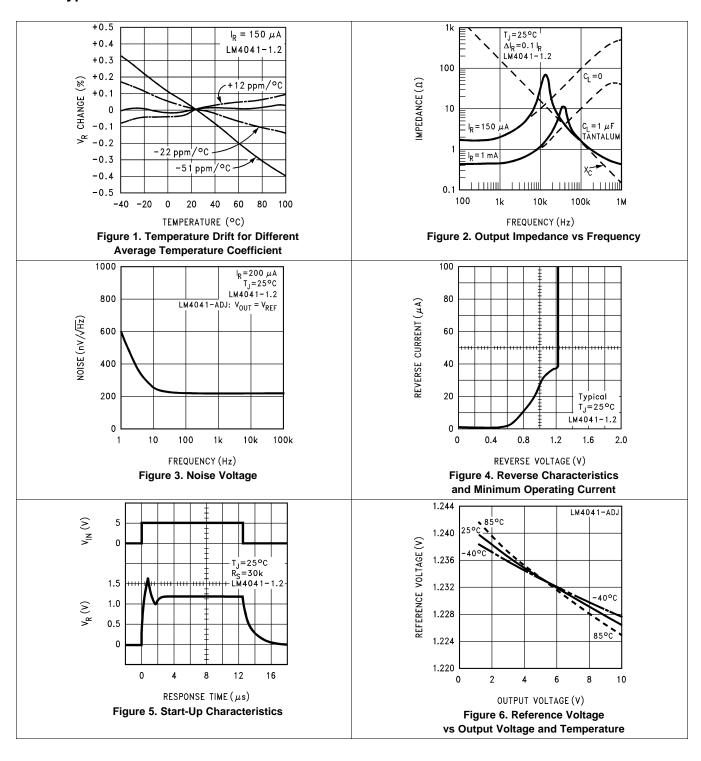
- (1) When V_{OUT} ≤ 1.6 V, the LM4041-N ADJ in the SOT-23 package must operate at reduced I_R. This is caused by the series resistance of the die attach between the die (–) output and the package (–) output pin. See the Output Saturation (SOT-23 only) curve in the Typical Characteristics section.
- (2) Limits are 100% production tested at 25°C. Limits over temperature are ensured through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate AOQL.
- (3) Typicals are at T_J = 25°C and represent most likely parametric norm.
- (4) Reference voltage and temperature coefficient will change with output voltage. See *Typical Characteristics* curves.
- (5) Load regulation is measured on pulse basis from no load to the specified load current. Ouput changes due to die temperature change must be taken into account separately.

Product Folder Links: LM4041-N LM4041-N-Q1

(6) Thermal hysteresis is defined as the difference in voltage measured at +25°C after cycling to temperature -40°C and the +25°C measurement after cycling to temperature +125°C.

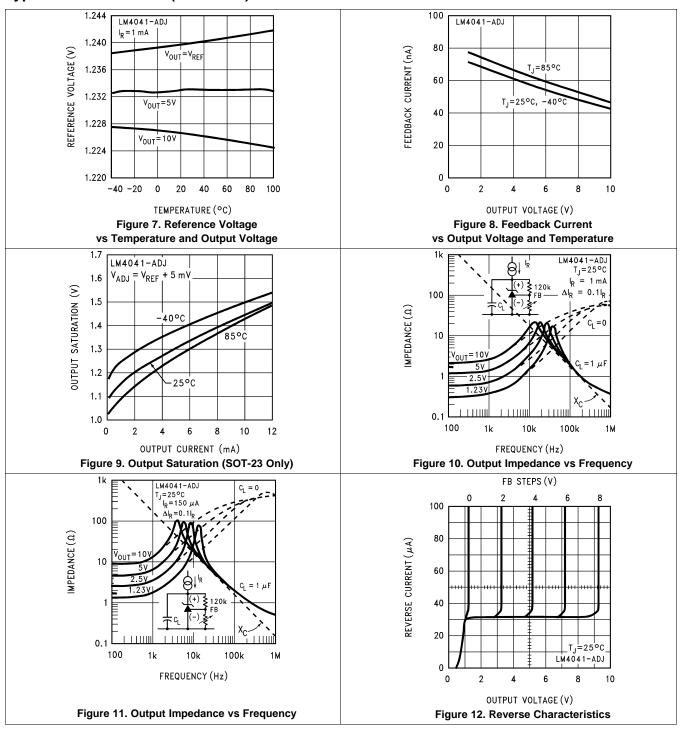


6.10 Typical Characteristics



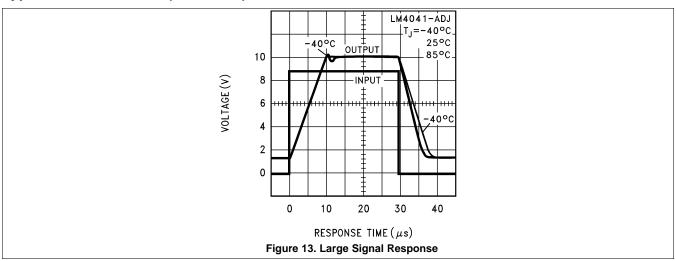


Typical Characteristics (continued)





Typical Characteristics (continued)





7 Parameter Measurement Information



Figure 14. Adjustable Output Test Circuit

Figure 15. Line Transient Test Circuit

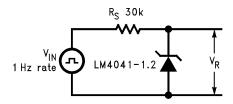


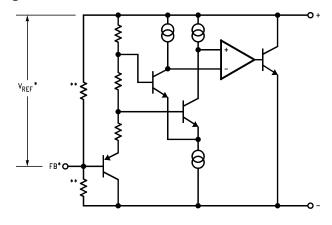
Figure 16. Start-Up and Shutdown Test Circuit

8 Detailed Description

8.1 Overview

The LM4041 is a precision micro-power shunt voltage reference available in both a fixed and output voltage and adjustable output voltage options. The part has three different packages available to meet small footprint requirements. It is also available in five different tolerance grades.

8.2 Functional Block Diagram



*LM4041-N ADJ only **LM4041-N 1.2 only

8.3 Feature Description

The LM4041 is effectively a precision Zener diode. The part requires a small quiescent current for regulation, and regulates the output voltage by shunting more or less current to ground, depending on input voltage and load. The only external component requirement is a resistor between the cathode and the input voltage to set the input current. An external capacitor can be used on the input or output, but is not required.

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8.4 Device Functional Modes

The LM4041 has fixed output voltage options as well as adjustable output voltage options. The fixed output parts can only be used in closed-loop operation, as the feedback is internal. The adjustable option parts are most commonly operated in closed-loop mode, where the feedback node is tied to the output voltage through a resistor divider. The output voltage will remain as long as I_R is between I_{RMIN} and I_{RMAX} ; see LM4041-N-xx 1.2 Electrical Characteristics (Industrial Temperature Range). This part can also be used in open-loop mode to act as a comparator, driving the feedback node from another voltage source.



9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The LM4041-N is a precision micro-power curvature-corrected bandgap shunt voltage reference. For space-critical applications, the LM4041-N is available in the sub-miniature SOT-23 and SC70 surface-mount package. The LM4041-N has been designed for stable operation without the need of an external capacitor connected between the + pin and the – pin. If, however, a bypass capacitor is used, the LM4041-N remains stable. Design effort is further reduced with the choice of either a fixed 1.2 V or an adjustable reverse breakdown voltage. The minimum operating current is 60 μ A for the LM4041-N 1.2 V and the LM4041-N ADJ. Both versions have a maximum operating current of 12 mA.

LM4041-Ns using the SOT-23 package have pin 3 connected as the (–) output through the die attach interface of the package. Therefore, pin 3 of the LM4041-N 1.2 must be left floating or connected to pin 2 and pin 3 of the LM4041-N ADJ pinout.

The LM4041-N devices using the SC70 package have pin 2 connected as the (–) output through the die attach interface of the package. Therefore, the LM4041-N pin 2 of the LM4041-N 1.2 must be left floating or connected to pin 1, and the pin 2 of the LM4041-N ADJ is the (–) output.

The typical thermal hysteresis specification is defined as the change in 25°C voltage measured after thermal cycling. The device is thermal cycled to temperature –40°C and then measured at +25°C. Next the device is thermal cycled to temperature 125°C and again measured at 25°C. The resulting V_{OUT} delta shift between the 25°C measurements is thermal hysteresis. Thermal hysteresis is common in precision references and is induced by thermal-mechanical package stress. Changes in environmental storage temperature, operating temperature and board mounting temperature are all factors that can contribute to thermal hysteresis.

In a conventional shunt regulator application (Figure 17), an external series resistor (R_S) is connected between the supply voltage and the LM4041-N. R_S determines the current that flows through the load (I_L) and the LM4041-N (I_Q). Because load current and supply voltage may vary, R_S must be small enough to supply at least the minimum acceptable I_Q to the LM4041-N even when the supply voltage is at its minimum and the load current is at its maximum value. When the supply voltage is at its maximum and I_L is at its minimum, R_S must be large enough so that the current flowing through the LM4041-N is less than 12 mA.

 R_S must be selected based on the supply voltage, (V_S), the desired load and operating current, (I_L and I_Q), and the reverse breakdown voltage of the LM4041-N, V_R .

$$\mathsf{R}_\mathsf{S} = \frac{\mathsf{V}_\mathsf{S} - \mathsf{V}_\mathsf{R}}{\mathsf{I}_\mathsf{L} + \mathsf{I}_\mathsf{Q}} \tag{1}$$

The output voltage of the LM4041-N SDJ can be adjusted to any value in the range of 1.24 V through 10 V. It is a function of the internal reference voltage (V_{REF}) and the ratio of the external feedback resistors as shown in Figure 19 . The output voltage is found using Equation 2.

$$V_0 = V_{REF}[(R2/R1) + 1]$$

where

•
$$V_0$$
 is the output voltage. (2)

The actual value of the internal V_{REF} is a function of V_O. The corrected V_{REF} is determined by Equation 3.

$$V_{REF} = \Delta V_O (\Delta V_{REF}/\Delta V_O) + V_Y$$

where

•
$$V_Y = 1.240 \text{ V}$$

• and
$$\Delta V_O = (V_O - V_Y)$$
 (3)



Application Information (continued)

 $\Delta V_{REF}/\Delta V_{O}$ is found in the electrical characteristics tables in the Specifications and is typically -1.55 mV/V. You can get a more accurate indication of the output voltage by replacing the value of V_{REF} in Equation 2 with the value found using Equation 3.

NOTE

The actual output voltage can deviate from that predicted using the typical value of ΔV_{REF} / ΔV_{O} in Equation 3. For C-grade parts, the worst-case ΔV_{REF} / ΔV_{O} is -2.5 mV/V. For D-grade parts, the worst-case $\Delta V_{REF} / \Delta V_{O}$ is -3.0 mV/V.

9.2 Typical Applications

9.2.1 Shunt Regulator

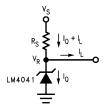


Figure 17. Shunt Regulator

9.2.1.1 Design Requirements

 $V_{IN} > V_{OUT}$

Select R_S with Equation 4.

$$I_{RMIN} < I_{R} < I_{RMAX} = 15 \text{ mA} \tag{4}$$

See the electrical characteristics tables in the Specifications for minimum operating current for each voltage option and grade.

9.2.1.2 Detailed Design Procedure

The resistor R_S must be selected such that current I_R remains in the operational region of the part for the entire V_{IN} range and load current range. At its maximum, the R_{S} must be small enough for I_{R} to remain above I_{RMN} . The other extreme is when V_{IN} at its maximum and the load at its minimum; the R_S must be large enough to maintain $I_R < I_{RMAX}$. If unsure, try using 0.1 mA $\leq I_R \leq$ 1 mA as starting point. Just remember the value of I_R varies with input and voltage load.

Use equations Equation 5 and Equation 6 to set R_S between R_{S_MIN} and R_{S_MAX}.

$$R_{S_MIN} = \frac{V_{IN_MAX} - V_{OUT}}{I_{LOAD_MIN} + I_{R_MAX}}$$
(5)

$$R_{S_MAX} = \frac{V_{IN_MIN} - V_{OUT}}{I_{LOAD_MAX} + I_{R_MIN}}$$
(6)



Typical Applications (continued)

9.2.1.3 Application Curve

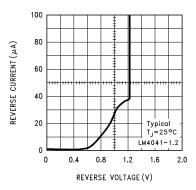
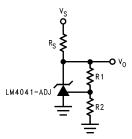


Figure 18. Reverse Characteristics and Minimum Operating Current

9.2.2 Adjustable Shunt Regulator



 $V_0 = V_{REF}[(R2/R1) + 1]$

Figure 19. Adjustable Shunt Regulator

9.2.2.1 Design Requirements

 $V_{IN} > V_{OUT}$

 $V_{OUT} = 2.5 V$

Select R_S with Equation 7.

 $I_{RMIN} < L_{R} < I_{RMAX}$

where

See the electrical characteristics tables in the *Specifications* for minimum operating current for each voltage option and grade.

9.2.2.2 Detail Design Procedure

Select a value of R_S based on the same method shown in *Detailed Design Procedure*.

Set feedback resistors R_1 and R_2 for a resistor divider on the equation shown in *Application Information* that is reproduced here as Equation 8.

$$V_{OUT} + V_{REF} \times ((R_2/R_1)+1)$$
 (8)

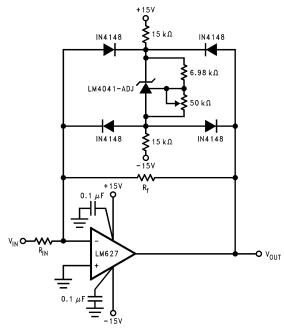
So, for a 2.5-V reference, of V_{REF} is 1.24 V, then R_2/R_1 = 1.01. Select R_2 = 1.01 k Ω and R_1 = 1.0 k Ω .

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Typical Applications (continued)

9.2.3 Bounded Amplifier



Bounded amplifier reduces saturation-induced delays and can prevent succeeding stage damage. Nominal clamping voltage is $\pm V_{\rm O}$ (the reverse breakdown voltage of the LM4041-N) +2 diode $V_{\rm F}$.

Figure 20. Bounded Amplifier

9.2.3.1 Design Requirements

Design an amplifier with output clamped at ±11.5 V.

9.2.3.2 Detail Design Procedure

With amplifier rails of ±15 V, the output can be bound to ±11.5 V with the LM4041 adjustable set for 10 V and two nominal diode voltage drops of 0.7 V.

$$V_{OUTBOUND} = 2 \times V_{FWD} + V_{Z}$$
 (9)

$$V_{OUTBOUND} = 1.4 \text{ V} + 10 \text{ V} \tag{10}$$

Select R_S = 15 k Ω to keep L_R low. Calculate L_R to confirm R_S selection.

Use Equation 11, but in this case, take the negative supply into account.

$$I_{R} = (V_{IN} - V_{OUT})/R \tag{11}$$

$$I_{R} = (V_{IN+} - V_{IN} - V_{OUT}) / R = (30 \text{ V} - 10 \text{ V}) / (R_{S1} + R_{S2}) = 20 \text{ V} / 30 \text{ k} \Omega = 0.667 \text{ mA}$$
(12)

This is an acceptable value for I_R that does not draw excessive current, but prevents the part from being starved for current.



Typical Applications (continued)

9.2.3.3 Application Curve

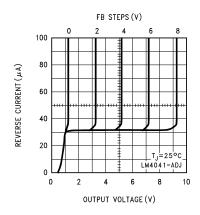


Figure 21. Reverse Characteristics

9.2.4 Voltage Level Detector

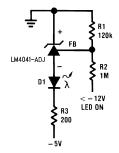


Figure 22. Voltage Level Detector

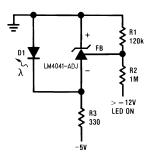


Figure 23. Voltage Level Detector

9.2.4.1 Design Procedure

Turn on an LED when voltage is above or below –12 V.

9.2.4.2 Detail Design Procedure

Use the LM4041 in an open-loop configuration, where the feedback node is tied to a voltage divider driven by the input signal. The voltage divider is set such that when the input signal is at -12 V, the feedback node is -1.24 V. The high gain of the LM4041 will enable it to act like a comparator.

9.2.5 Precision Current Sink and Source

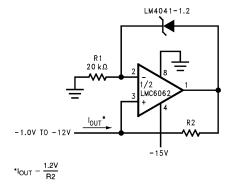


Figure 24. Precision 1-µA to 1-mA Current Sink

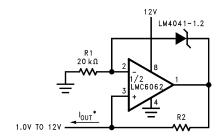


Figure 25. Precision 1-µA to 1-mA Current Sources



9.2.5.1 Design Requirements

Create precision 1-mA current sink and 1-mA current source.

9.2.5.2 Detailed Design Procedure

Set R1 such that the current through the shunt reference, I_R , is greater than I_{RMIN} .

$$I_{OUT} = V_{OUT} / R_2$$

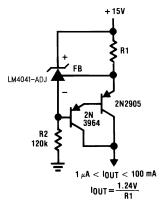
where

V_{OUT} is the voltage drop across the shunt reference

(13)

In this case, $I_{OUT} = 1.2 / R_2$.

9.2.6 100-mA Current Source



*D1 can be any LED, $V_F = 1.5 \text{ V}$ to 2.2 V at 3 mA. D1 may act as an indicator. D1 will be on if $I_{THRESHOLD}$ falls below the threshold current, except with I = 0.

Figure 26. Current Source

9.2.6.1 Design Requirements

Create 100-mA current source.

9.2.6.2 Detailed Design Procedure

 $I_{OUT} = V_{OUT} / R_1$

where

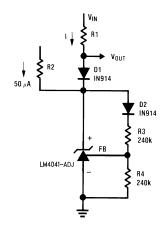
 $\bullet \quad V_{\text{OUT}}$ is the voltage drop across the shunt reference.

(14)

In this case, $I_{OUT} = 1.24 / R_1$.



9.2.7 LM4041 in Clamp Circuits



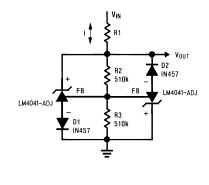


Figure 27. Fast Positive Clamp 2.4 V + V_{D1}

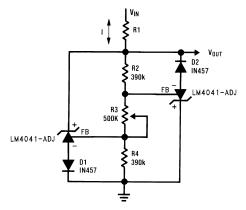


Figure 28. Bidirectional Clamp ±2.4 V

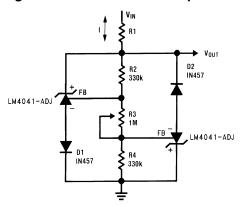


Figure 29. Bidirectional Adjustable Clamp ±18 V to Figure 30. Bidirectional Adjustable Clamp ±2.4 V to ±2.4 V

9.2.7.1 Design Requirements

Create adjustable clamping circuits using the LM4041.

9.2.7.2 Detailed Design Procedure

Use the LM4041 in open-loop, as a 1.24-V diode that can be on or off based on the voltage at the feedback. See Figure 27 through Figure 30 for examples.

Submit Documentation Feedback

Product Folder Links: LM4041-N LM4041-N-Q1



9.2.8 Floating Current Detector

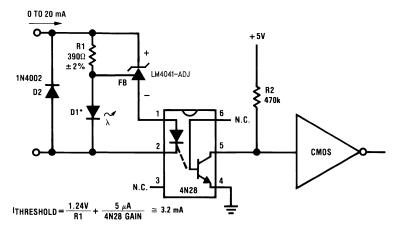


Figure 31. Simple Floating Current Detector

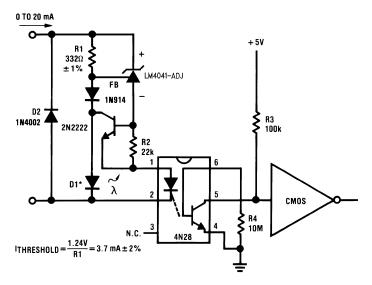


Figure 32. Precision Floating Current Detector

9.2.8.1 Design Requirement

Create a floating current detector using the LM4041.

9.2.8.2 Detailed Design Procedure

Use the LM4041 as a voltage dependent diode, which turns on and off based on the voltage drop across R1. See Figure 31 and Figure 32 for examples.



10 Power Supply Recommendations

While a bypass capacitor is not required on the input voltage line, TI recommends reducing noise on the input which could affect the output. A 0.1-µF ceramic capacitor or larger is recommended.

Layout 11

11.1 Layout Guidelines

Place external components as close to the device as possible. Place R_S close the cathode, as well as the input bypass capacitor, if used. Keep feedback resistor close the device whenever possible.

11.2 Layout Example

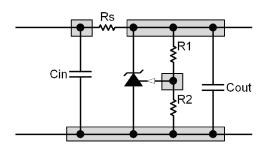


Figure 33. Recommended Layout

Submit Documentation Feedback

Product Folder Links: LM4041-N LM4041-N-Q1



12 Device and Documentation Support

12.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
LM4041-N	Click here	Click here	Click here	Click here	Click here
LM4041-N-Q1	Click here	Click here	Click here	Click here	Click here

12.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.3 Trademarks

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

12.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.5 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.





9-Mar-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM4041AIM3-1.2	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	R1A	
LM4041AIM3-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1A	Samples
LM4041AIM3X-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1A	Sample
LM4041AIZ-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 85	4041A IZ1.2	Sample
LM4041BIM3-1.2	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	R1B	
LM4041BIM3-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1B	Sample
LM4041BIM3X-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1B	Sample
LM4041BIM7-1.2	NRND	SC70	DCK	5	1000	TBD	Call TI	Call TI	-40 to 85	R1B	
LM4041BIM7-1.2/NOPB	ACTIVE	SC70	DCK	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1B	Sample
LM4041BIM7X-1.2/NOPB	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1B	Sample
LM4041BIZ-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 85	4041B IZ1.2	Sample
LM4041CEM3-1.2	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 125	R1C	
LM4041CEM3-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	R1C	Sample
LM4041CEM3-ADJ	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 125	RAC	
LM4041CEM3-ADJ/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RAC	Sample
LM4041CEM3X-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	R1C	Sample
LM4041CEM3X-ADJ	NRND	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	-40 to 125	RAC	
LM4041CEM3X-ADJ/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RAC	Sample
LM4041CIM3-1.2	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	R1C	
LM4041CIM3-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1C	Sample





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM4041CIM3-ADJ	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	RAC	
LM4041CIM3-ADJ/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RAC	Samples
LM4041CIM3X-1.2	NRND	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	-40 to 85	R1C	
LM4041CIM3X-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1C	Samples
LM4041CIM3X-ADJ/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RAC	Samples
LM4041CIM7-1.2/NOPB	ACTIVE	SC70	DCK	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1C	Samples
LM4041CIM7-ADJ	NRND	SC70	DCK	5	1000	TBD	Call TI	Call TI	-40 to 85	RAC	
LM4041CIM7-ADJ/NOPB	ACTIVE	SC70	DCK	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RAC	Samples
LM4041CIM7X-1.2/NOPB	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1C	Samples
LM4041CIM7X-ADJ/NOPB	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RAC	Samples
LM4041CIZ-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 85	4041C IZ1.2	Samples
LM4041CIZ-ADJ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 85	4041C IZADJ	Samples
LM4041DEM3-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	R1D	Samples
LM4041DEM3-ADJ	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 125	RAD	
LM4041DEM3-ADJ/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RAD	Samples
LM4041DEM3X-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	R1D	Samples
LM4041DEM3X-ADJ/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RAD	Samples
LM4041DIM3-1.2	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	R1D	
LM4041DIM3-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1D	Samples
LM4041DIM3-ADJ	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	RAD	



9-Mar-2018

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM4041DIM3-ADJ/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RAD	Samples
LM4041DIM3X-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1D	Samples
LM4041DIM3X-ADJ	NRND	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	-40 to 85	RAD	
LM4041DIM3X-ADJ/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RAD	Samples
LM4041DIM7-1.2/NOPB	ACTIVE	SC70	DCK	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1D	Samples
LM4041DIM7-ADJ/NOPB	ACTIVE	SC70	DCK	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RAD	Samples
LM4041DIM7X-1.2/NOPB	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1D	Samples
LM4041DIM7X-ADJ/NOPB	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RAD	Samples
LM4041DIZ-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 85	4041D IZ1.2	Samples
LM4041DIZ-ADJ/LFT1	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type		4041D IZADJ	Samples
LM4041DIZ-ADJ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 85	4041D IZADJ	Samples
LM4041EEM3-1.2	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 125	R1E	
LM4041EEM3-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	R1E	Samples
LM4041EEM3X-1.2	NRND	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	-40 to 125	R1E	
LM4041EEM3X-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	R1E	Samples
LM4041EIM3-1.2	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	R1E	
LM4041EIM3-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1E	Samples
LM4041EIM3X-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1E	Samples
LM4041EIM7-1.2/NOPB	ACTIVE	SC70	DCK	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1E	Samples
LM4041EIM7X-1.2/NOPB	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	R1E	Samples





9-Mar-2018

Orderable Device	Status	Package Type	_	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM4041QAIM3-1.2/NO	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RQA	Sample
LM4041QBIM3-1.2/NO	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RQB	Sample
LM4041QCEM3-1.2NO	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RQC	Sample
LM4041QCEM3-ADJ/NO	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RZC	Sample
LM4041QCEM3X-1.2NO	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RQC	Sample
LM4041QCIM3-1.2/NO	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RQC	Sample
LM4041QCIM3-ADJ/NO	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RZC	Sample
LM4041QDEM3-1.2/NO	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RQD	Sample
LM4041QDEM3-ADJ/NO	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RZD	Sample
LM4041QDIM3-1.2/NO	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RQD	Sample
LM4041QDIM3-ADJ/NO	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RZD	Sample
LM4041QEEM3-1.2/NO	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RQE	Sample
LM4041QEEM3X-1.2NO	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RQE	Sample
LM4041QEIM3-1.2/NO	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RQE	Sample

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



PACKAGE OPTION ADDENDUM

9-Mar-2018

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF LM4041-N, LM4041-N-Q1:

Catalog: LM4041-N

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Automotive: LM4041-N-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM4041AIM3-1.2	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041AIM3-1.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041AIM3X-1.2/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041BIM3-1.2	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041BIM3-1.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041BIM3X-1.2/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041BIM7-1.2	SC70	DCK	5	1000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041BIM7-1.2/NOPB	SC70	DCK	5	1000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041BIM7X-1.2/NOPB	SC70	DCK	5	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041CEM3-1.2	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041CEM3-1.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041CEM3-ADJ	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041CEM3-ADJ/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041CEM3X-1.2/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041CEM3X-ADJ	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041CEM3X-ADJ/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041CIM3-1.2	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3



PACKAGE MATERIALS INFORMATION

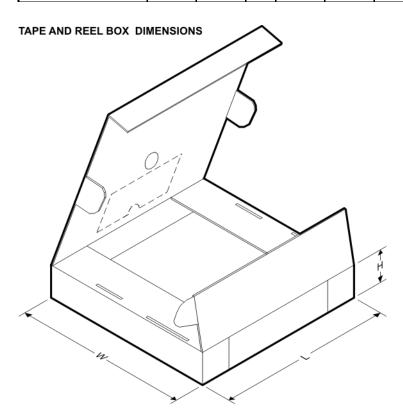
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Device	Package	Package	Pins	SPQ	Reel	Reel	Α0	В0	K0	P1	w	Pin1
201100	Туре	Drawing		O . A	Diameter (mm)		(mm)	(mm)	(mm)	(mm)	(mm)	Quadrant
LM4041CIM3-1.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041CIM3-ADJ	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041CIM3-ADJ/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041CIM3X-1.2	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041CIM3X-1.2/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041CIM3X-ADJ/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041CIM7-1.2/NOPB	SC70	DCK	5	1000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041CIM7-ADJ	SC70	DCK	5	1000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041CIM7-ADJ/NOPB	SC70	DCK	5	1000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041CIM7X-1.2/NOPB	SC70	DCK	5	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041CIM7X-ADJ/NOP B	SC70	DCK	5	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041DEM3-1.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041DEM3-ADJ	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041DEM3-ADJ/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041DEM3X-1.2/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
M4041DEM3X-ADJ/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041DIM3-1.2	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041DIM3-1.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041DIM3-ADJ	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041DIM3-ADJ/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041DIM3X-1.2/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041DIM3X-ADJ	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041DIM3X-ADJ/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041DIM7-1.2/NOPB	SC70	DCK	5	1000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041DIM7-ADJ/NOPB	SC70	DCK	5	1000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041DIM7X-1.2/NOPB	SC70	DCK	5	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041DIM7X-ADJ/NOP B	SC70	DCK	5	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041EEM3-1.2	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041EEM3-1.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041EEM3X-1.2	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041EEM3X-1.2/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041EIM3-1.2	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041EIM3-1.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041EIM3X-1.2/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041EIM7-1.2/NOPB	SC70	DCK	5	1000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041EIM7X-1.2/NOPB	SC70	DCK	5	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM4041QAIM3-1.2/NO	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041QBIM3-1.2/NO	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041QCEM3-1.2NO	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3

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Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM4041QCEM3-ADJ/NO	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041QCEM3X-1.2NO	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041QCIM3-1.2/NO	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041QCIM3-ADJ/NO	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041QDEM3-1.2/NO	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041QDEM3-ADJ/NO	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041QDIM3-1.2/NO	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041QDIM3-ADJ/NO	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041QEEM3-1.2/NO	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041QEEM3X-1.2NO	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4041QEIM3-1.2/NO	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM4041AIM3-1.2	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041AIM3-1.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041AIM3X-1.2/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041BIM3-1.2	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041BIM3-1.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041BIM3X-1.2/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0



PACKAGE MATERIALS INFORMATION

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM4041BIM7-1.2	SC70	DCK	5	1000	210.0	185.0	35.0
LM4041BIM7-1.2/NOPB	SC70	DCK	5	1000	210.0	185.0	35.0
LM4041BIM7X-1.2/NOPB	SC70	DCK	5	3000	210.0	185.0	35.0
LM4041CEM3-1.2	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041CEM3-1.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041CEM3-ADJ	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041CEM3-ADJ/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041CEM3X-1.2/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041CEM3X-ADJ	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041CEM3X-ADJ/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041CIM3-1.2	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041CIM3-1.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041CIM3-ADJ	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041CIM3-ADJ/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041CIM3X-1.2	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041CIM3X-1.2/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041CIM3X-ADJ/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041CIM7-1.2/NOPB	SC70	DCK	5	1000	210.0	185.0	35.0
LM4041CIM7-ADJ	SC70	DCK	5	1000	210.0	185.0	35.0
LM4041CIM7-ADJ/NOPB	SC70	DCK	5	1000	210.0	185.0	35.0
LM4041CIM7X-1.2/NOPB	SC70	DCK	5	3000	210.0	185.0	35.0
LM4041CIM7X-ADJ/NOPB	SC70	DCK	5	3000	210.0	185.0	35.0
LM4041DEM3-1.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041DEM3-ADJ	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041DEM3-ADJ/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041DEM3X-1.2/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041DEM3X-ADJ/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041DIM3-1.2	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041DIM3-1.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041DIM3-ADJ	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041DIM3-ADJ/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041DIM3X-1.2/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041DIM3X-ADJ	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041DIM3X-ADJ/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041DIM7-1.2/NOPB	SC70	DCK	5	1000	210.0	185.0	35.0
LM4041DIM7-ADJ/NOPB	SC70	DCK	5	1000	210.0	185.0	35.0
LM4041DIM7X-1.2/NOPB	SC70	DCK	5	3000	210.0	185.0	35.0
LM4041DIM7X-ADJ/NOPB	SC70	DCK	5	3000	210.0	185.0	35.0
LM4041EEM3-1.2	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041EEM3-1.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041EEM3X-1.2	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041EEM3X-1.2/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0



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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM4041EIM3-1.2	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041EIM3-1.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041EIM3X-1.2/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041EIM7-1.2/NOPB	SC70	DCK	5	1000	210.0	185.0	35.0
LM4041EIM7X-1.2/NOPB	SC70	DCK	5	3000	210.0	185.0	35.0
LM4041QAIM3-1.2/NO	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041QBIM3-1.2/NO	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041QCEM3-1.2NO	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041QCEM3-ADJ/NO	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041QCEM3X-1.2NO	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041QCIM3-1.2/NO	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041QCIM3-ADJ/NO	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041QDEM3-1.2/NO	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041QDEM3-ADJ/NO	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041QDIM3-1.2/NO	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041QDIM3-ADJ/NO	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041QEEM3-1.2/NO	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4041QEEM3X-1.2NO	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4041QEIM3-1.2/NO	SOT-23	DBZ	3	1000	210.0	185.0	35.0



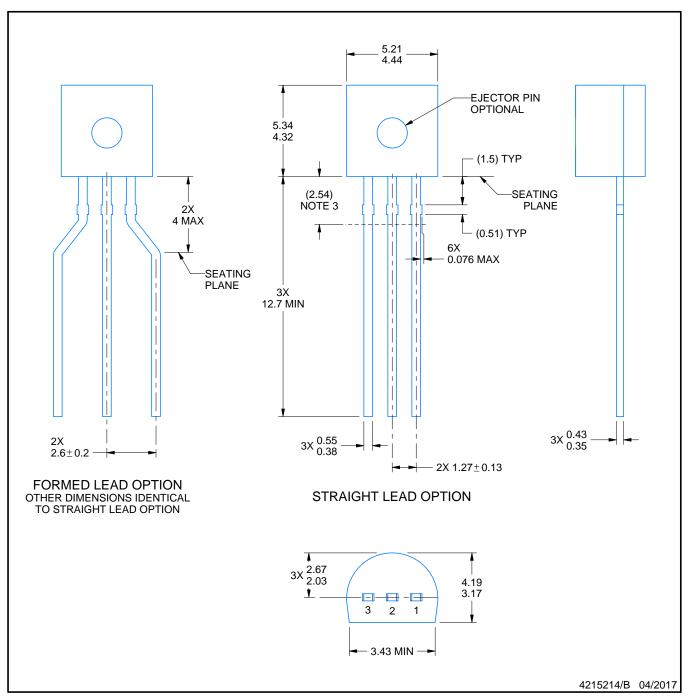
Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040001-2/F



TO-92 - 5.34 mm max height

TO-92



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.
- 3. Lead dimensions are not controlled within this area.4. Reference JEDEC TO-226, variation AA.
- 5. Shipping method:

 - a. Straight lead option available in bulk pack only.
 b. Formed lead option available in tape and reel or ammo pack.
 - c. Specific products can be offered in limited combinations of shipping medium and lead options.
 - d. Consult product folder for more information on available options.



TO-92





TO-92





DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AA.



DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.





Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4203227/C





SMALL OUTLINE TRANSISTOR



NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 This drawing is subject to change without notice.
 Reference JEDEC registration TO-236, except minimum foot length.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 4. Publication IPC-7351 may have alternate designs.5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 7. Board assembly site may have different recommendations for stencil design.



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